WHAT IS CLAIMED:

1. An adhesive comprising a sprayable adhesive composition having a viscosity within the range of 0.5 Pa.s to 5.0 Pa.s, containing at least one colored filler present in an amount up to 50% by weight of the adhesive composition, in which the adhesive is an epoxy resin or a combination of an electron donor resin and an electron acceptor resin.
2. The adhesive according to claim 1 in which the filler is carbon black.
3. A method for laser marking the inactive surface of a semiconductor silicon die or wafer comprising
   (a) providing a sprayable adhesive composition having a viscosity within the range of 0.5 Pa.s to 5.0 Pa.s, containing at least one colored filler present in an amount up to 50% by weight of the adhesive composition,
   (b) spraying the adhesive composition onto the inactive surface of the semiconductor silicon die or wafer to a thickness within the range of 12.5 μm to 150 μm
   (c) curing the adhesive composition
   (d) marking the die or wafer by using a laser to burn or cut a mark or fiducial into the adhesive.
4. The method according to claim 3 in which the sprayable adhesive is an epoxy resin or a combination of an electron donor resin and an electron acceptor resin.